

# DATA SHEET

Datasheet.World

## **74LVC04A** Hex inverter

Product specification  
Supersedes data of 2003 Feb 24

2003 Sep 04

## Hex inverter

## 74LVC04A

## FEATURES

- 5 V tolerant inputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- Complies with JEDEC standard no. 8-1A
- ESD protection:  
HBM EIA/JESD22-A114-A exceeds 2000 V  
MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from  $-40$  to  $+85$  °C and  $-40$  to  $+125$  °C.

## DESCRIPTION

The 74LVC04A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 and 5 V environment.

The 74LVC04A provides six inverting buffers.

## QUICK REFERENCE DATA

GND = 0 V;  $T_{amb} = 25$  °C;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	$C_L = 50$ pF; $V_{CC} = 3.3$ V	2.1	ns
$C_I$	input capacitance		4.0	pF
$C_{PD}$	power dissipation capacitance per gate	$V_{CC} = 3.3$ V; notes 1 and 2	15	pF

## Notes

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$N$  = total load switching outputs;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

2. The condition is  $V_I = \text{GND to } V_{CC}$ .

## FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	nY
L	H
H	L

## Note

1. H = HIGH voltage level;  
L = LOW voltage level.

## Hex inverter

## 74LVC04A

## ORDERING INFORMATION

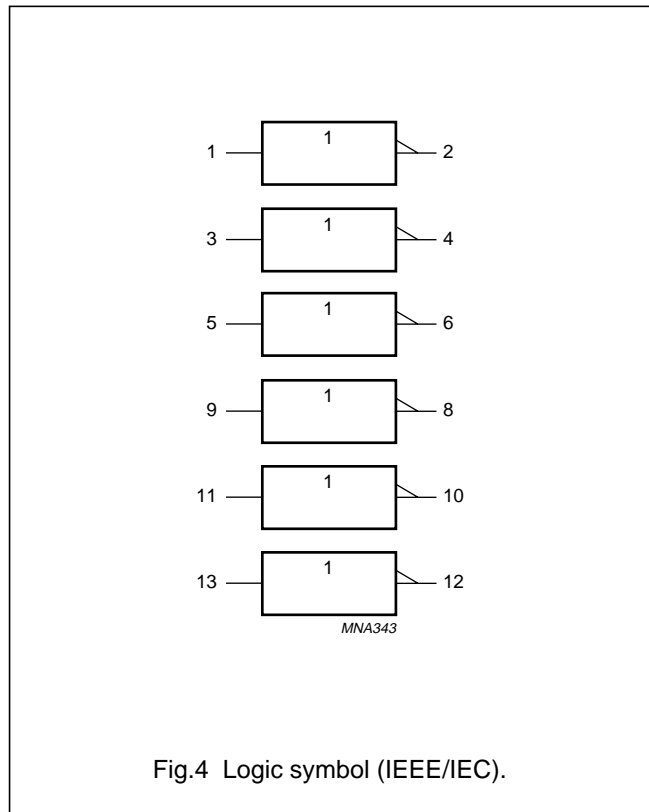
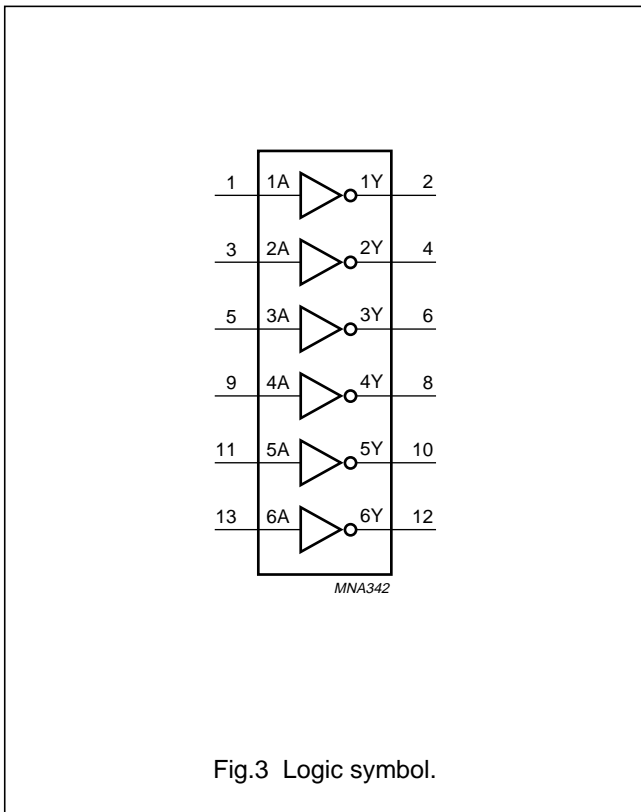
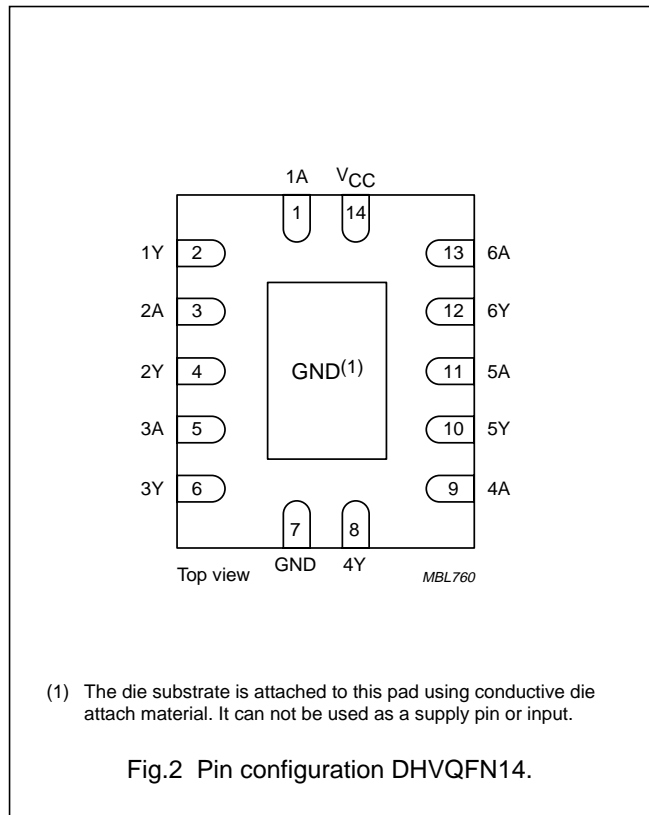
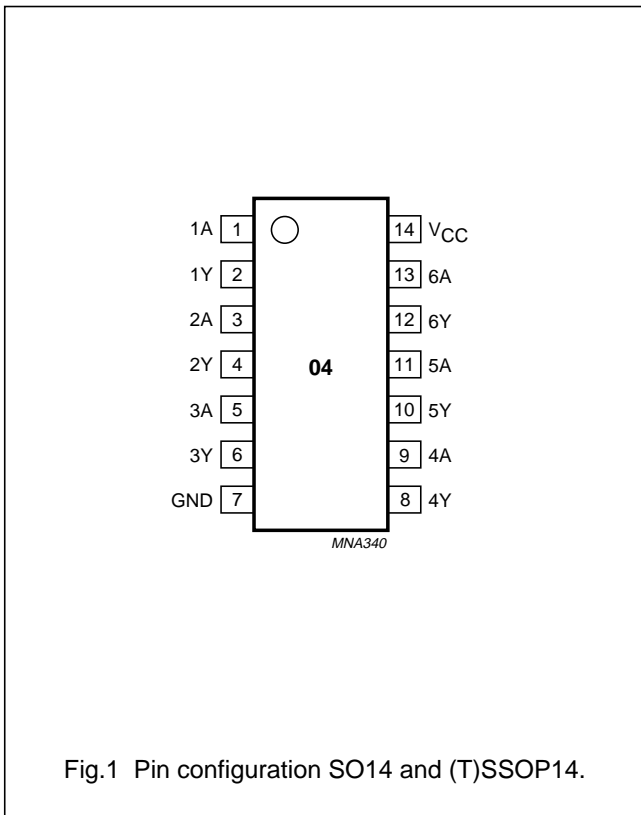
TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC04AD	-40 to +125 °C	14	SO14	plastic	SOT108-1
74LVC04ADB	-40 to +125 °C	14	SSOP14	plastic	SOT337-1
74LVC04APW	-40 to +125 °C	14	TSSOP14	plastic	SOT402-1
74LVC04ABQ	-40 to +125 °C	14	DHVQFN14	plastic	SOT762-1

## PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1Y	data output
3	2A	data input
4	2Y	data output
5	3A	data input
6	3Y	data output
7	GND	ground (0 V)
8	4Y	data output
9	4A	data input
10	5Y	data output
11	5A	data input
12	6Y	data output
13	6A	data input
14	V <sub>CC</sub>	supply voltage

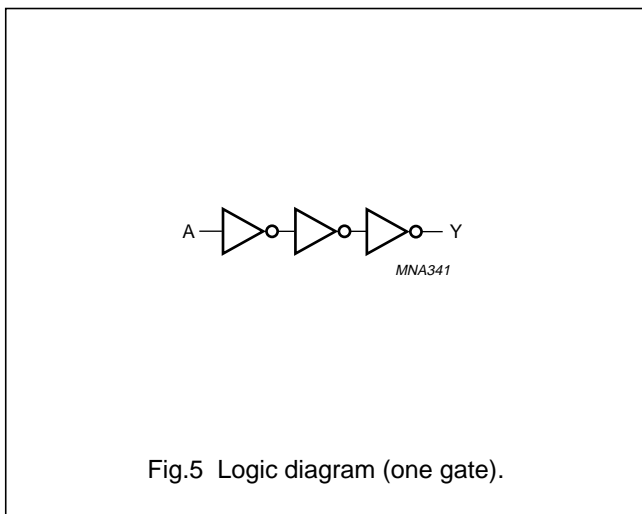
Hex inverter

74LVC04A



Hex inverter

74LVC04A



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CC</sub>	supply voltage	for maximum speed performance	2.7	3.6	V
		for low-voltage applications	1.2	3.6	V
V <sub>I</sub>	input voltage		0	5.5	V
V <sub>O</sub>	output voltage		0	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
t <sub>r</sub> , t <sub>f</sub>	input rise and fall times	V <sub>CC</sub> = 1.2 to 2.7 V	0	20	ns/V
		V <sub>CC</sub> = 2.7 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the absolute maximum rating system (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CC</sub>	supply voltage		-0.5	+6.5	V
I <sub>IK</sub>	input diode current	V <sub>I</sub> < 0	-	-50	mA
V <sub>I</sub>	input voltage	note 1	-0.5	+6.5	V
I <sub>OK</sub>	output diode current	V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0	-	±50	mA
V <sub>O</sub>	output voltage	note 1	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>O</sub>	output source or sink current	V <sub>O</sub> = 0 to V <sub>CC</sub>	-	±50	mA
I <sub>CC</sub> , I <sub>GND</sub>	V <sub>CC</sub> or GND current		-	±100	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	power dissipation per package	T <sub>amb</sub> = -40 to +125 °C; note 2	-	500	mW

Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- For SO14 packages: above 70 °C derate linearly with 8 mW/K.  
 For SSOP14 and TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.  
 For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

## Hex inverter

## 74LVC04A

**DC CHARACTERISTICS**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		1.2	V <sub>CC</sub>	-	-	V
			2.7 to 3.6	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage		1.2	-	-	GND	V
			2.7 to 3.6	-	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -100 μA	2.7 to 3.6	V <sub>CC</sub> - 0.2	-	-	V
		I <sub>O</sub> = -12 mA	2.7	V <sub>CC</sub> - 0.5	-	-	V
		I <sub>O</sub> = -18 mA	3.0	V <sub>CC</sub> - 0.6	-	-	V
		I <sub>O</sub> = -24 mA	3.0	V <sub>CC</sub> - 0.8	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 100 μA	2.7 to 3.6	-	-	0.2	V
		I <sub>O</sub> = 12 mA	2.7	-	-	0.4	V
		I <sub>O</sub> = 24 mA	3.0	-	-	0.55	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND	3.6	-	±0.1	±5	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	3.6	-	0.1	10	μA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0	2.7 to 3.6	-	5	500	μA

## Hex inverter

## 74LVC04A

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		1.2	V <sub>CC</sub>	–	–	V
			2.7 to 3.6	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -100 μA	2.7 to 3.6	V <sub>CC</sub> - 0.3	–	–	V
		I <sub>O</sub> = -12 mA	2.7	V <sub>CC</sub> - 0.65	–	–	V
		I <sub>O</sub> = -18 mA	3.0	V <sub>CC</sub> - 0.75	–	–	V
		I <sub>O</sub> = -24 mA	3.0	V <sub>CC</sub> - 1	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 100 μA	2.7 to 3.6	–	–	0.3	V
		I <sub>O</sub> = 12 mA	2.7	–	–	0.6	V
		I <sub>O</sub> = 24 mA	3.0	–	–	0.8	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND	3.6	–	–	±20	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	3.6	–	–	40	μA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0	2.7 to 3.6	–	–	5000	μA

**Note**

1. All typical values are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.

Hex inverter

74LVC04A

AC CHARACTERISTICS

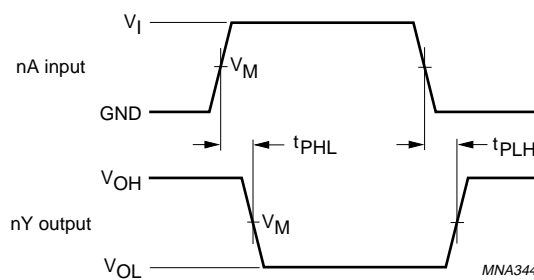
GND = 0 V;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		WAVEFORMS	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 6 and 7	1.2	–	14	–	ns
			2.7	1.0	2.2	5.5	ns
			3.0 to 3.6	1.0	1.9	4.5	ns
t <sub>sk(0)</sub>	skew	note 2	3.0 to 3.6	–	–	1.0	ps
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 6 and 7	1.2	–	–	–	ns
			2.7	1.0	–	7.0	ns
			3.0 to 3.6	1.0	–	6.0	ns
t <sub>sk(0)</sub>	skew	note 2	3.0 to 3.6	–	–	1.5	ps

Notes

1. All typical values are measured at V<sub>CC</sub> = 3.3 V.
2. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

AC WAVEFORMS



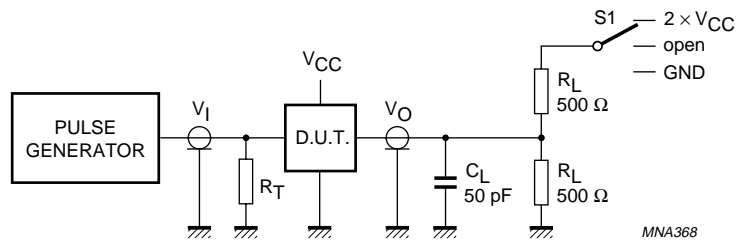
V<sub>M</sub> = 1.5 V at V<sub>CC</sub> ≥ 2.7 V;  
 V<sub>M</sub> = 0.5V<sub>CC</sub> at V<sub>CC</sub> < 2.7 V;  
 V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage drop that occur with the output load.

Fig.6 The input nA to output nY propagation delays.



Hex inverter

74LVC04A



$V_{CC}$	$V_I$	$t_{PLH}/t_{PHL}$
1.2 V	$V_{CC}$	open
2.7 V	2.7 V	open
3.0 to 3.6 V	2.7 V	open

Definitions for test circuits:

$R_L$  = Load resistor.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig.7 Load circuitry for switching times.

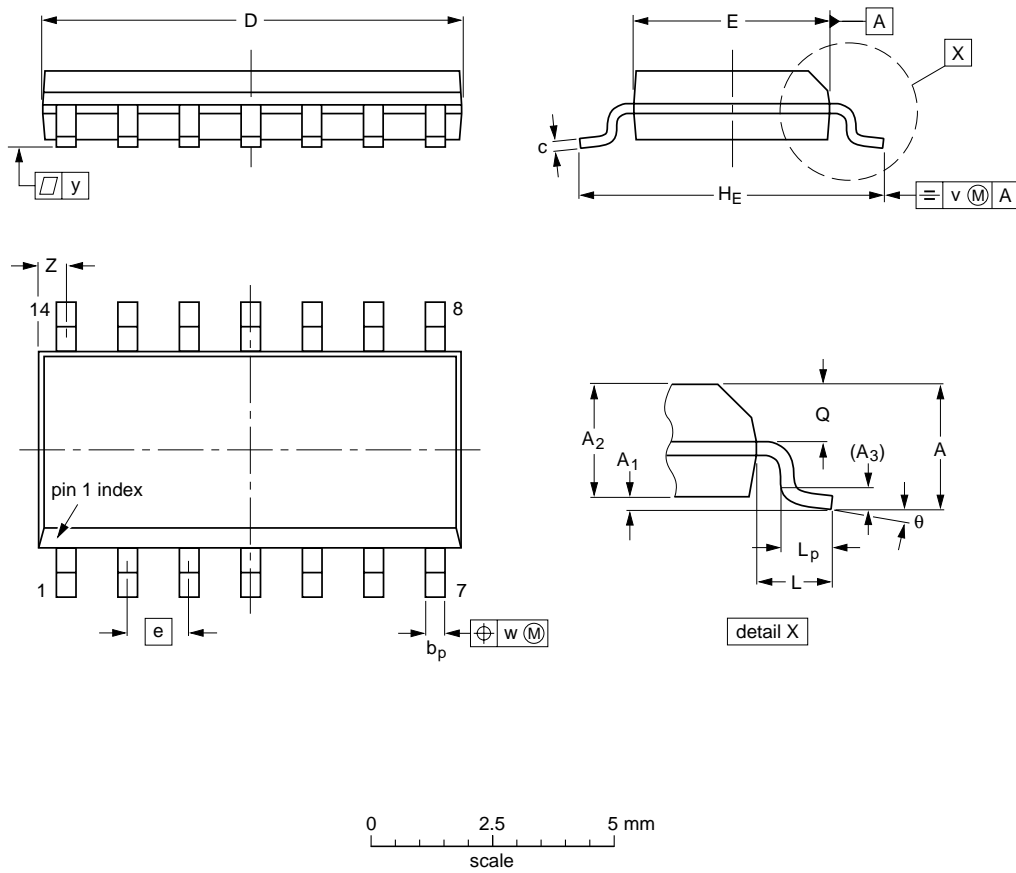
Hex inverter

74LVC04A

PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	$\theta$
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

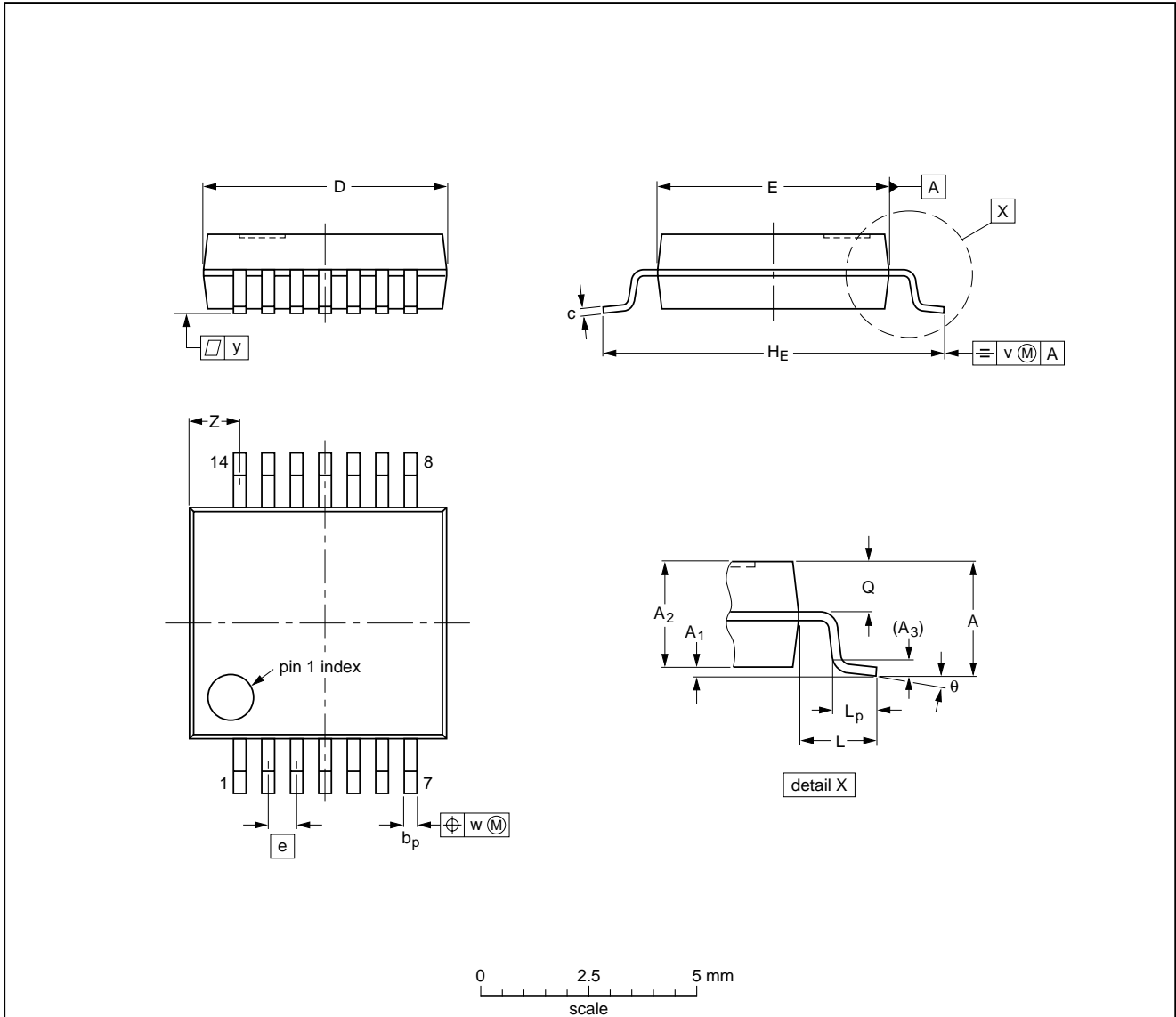
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT108-1	076E06	MS-012			99-12-27 03-02-19

Hex inverter

74LVC04A

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

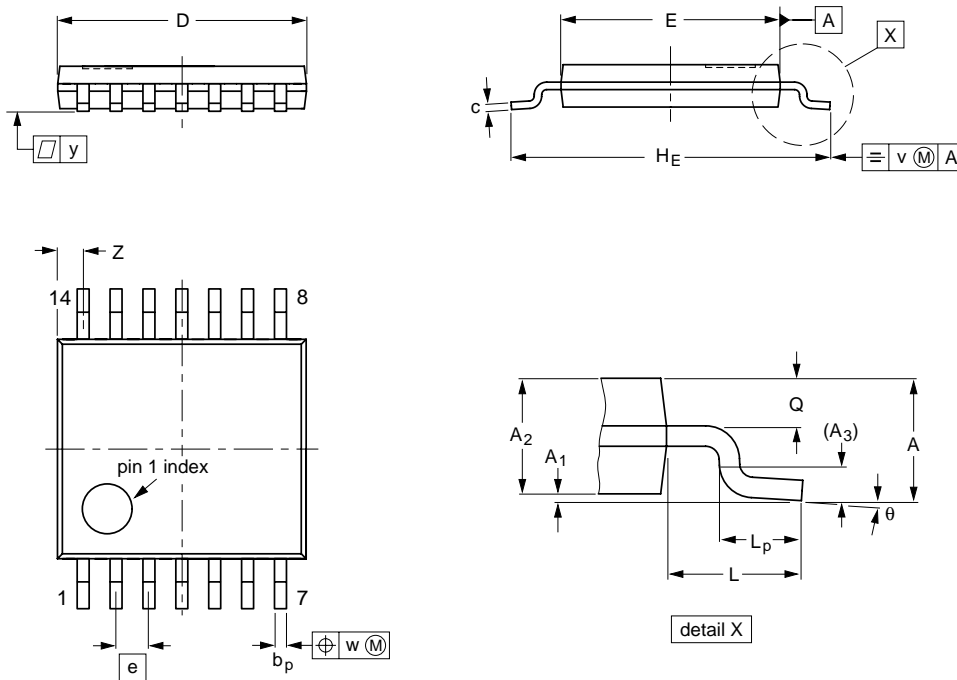
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	IEC	JEDEC	JEITA			
SOT337-1		MO-150				99-12-27 03-02-19

Hex inverter

74LVC04A

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

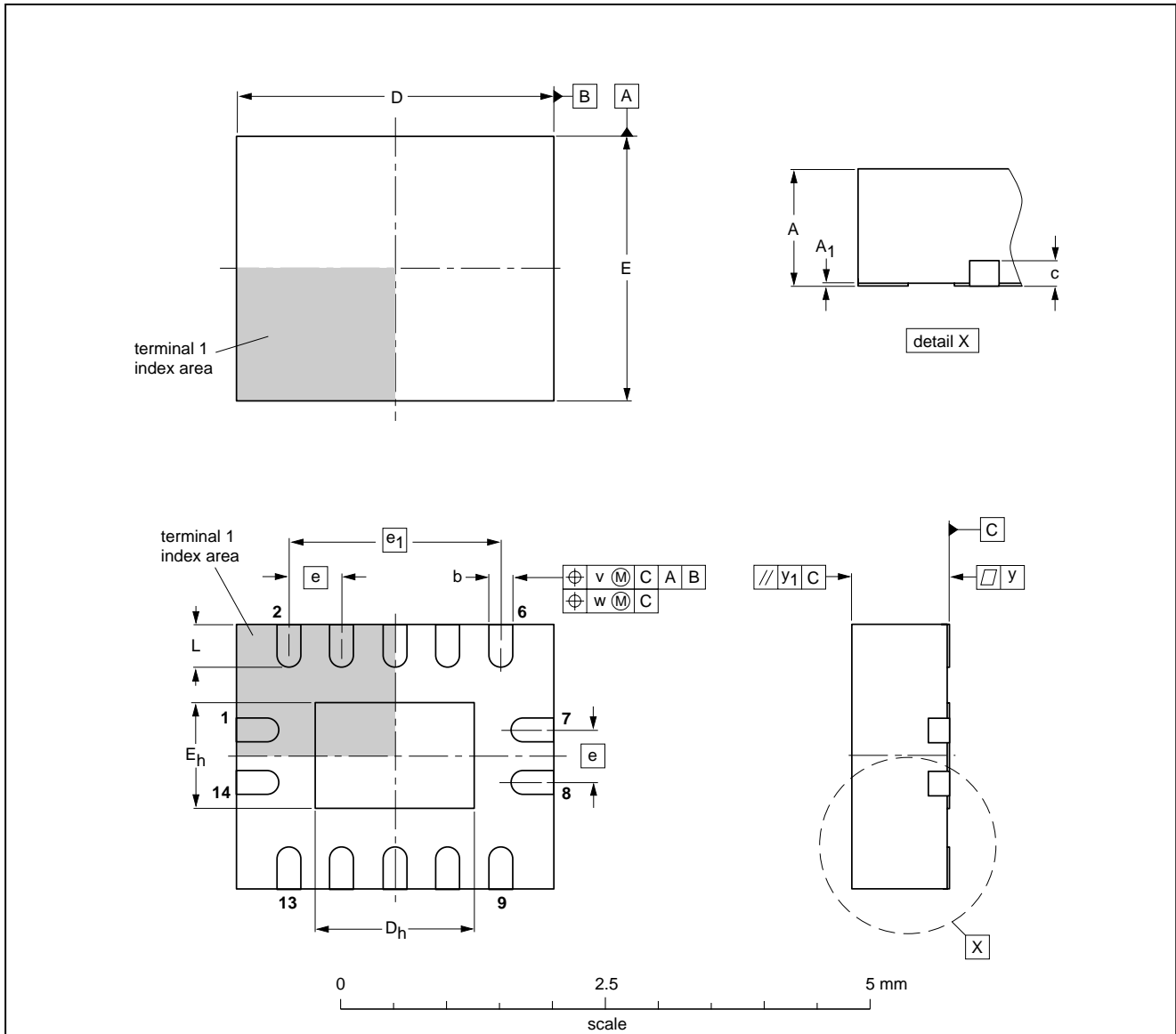
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	IEC	JEDEC	JEITA			
SOT402-1		MO-153				99-12-27 03-02-18

Hex inverter

74LVC04A

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1



DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	1.65 1.35	2.6 2.4	1.15 0.85	0.5	2	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT762-1	---	MO-241	---		02-10-17 03-01-27

## Hex inverter

74LVC04A

## DATA SHEET STATUS

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I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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